

OCMOS FET PS7141-2A,PS7141L-2A

8-PIN DIP, 400 V BREAK DOWN VOLTAGE

NORMALLY OPEN TYPE

-NEPOC Series-

Solid State Relay

2-ch Optical Coupled MOS FET

DESCRIPTION

The PS7141-2A and PS7141L-2A are solid state relays containing GaAs LEDs on the light emitting side (input side) and MOS FETs on the output side.

They are suitable for analog signal control because of their low offset and high linearity. The PS7141L-2A has a surface mount type lead.

FEATURES

- 2 channel type (1 a + 1 a output)
- Low LED operating current (IF = 2 mA)
- Designed for AC/DC switching line changer
- Small package (8-pin DIP)
- Low offset voltage
- Ordering number of taping product : PS7141L-2A-E3, E4: 1 000 pcs/reel

<R> • Pb-Free product

- Safety standards
 - UL approved: File No. E72422
 - BSI approved: No. 8245/8246
 - CSA approved: No. CA 101391

APPLICATIONS

- Exchange equipment
- Measurement equipment
- FA/OA equipment

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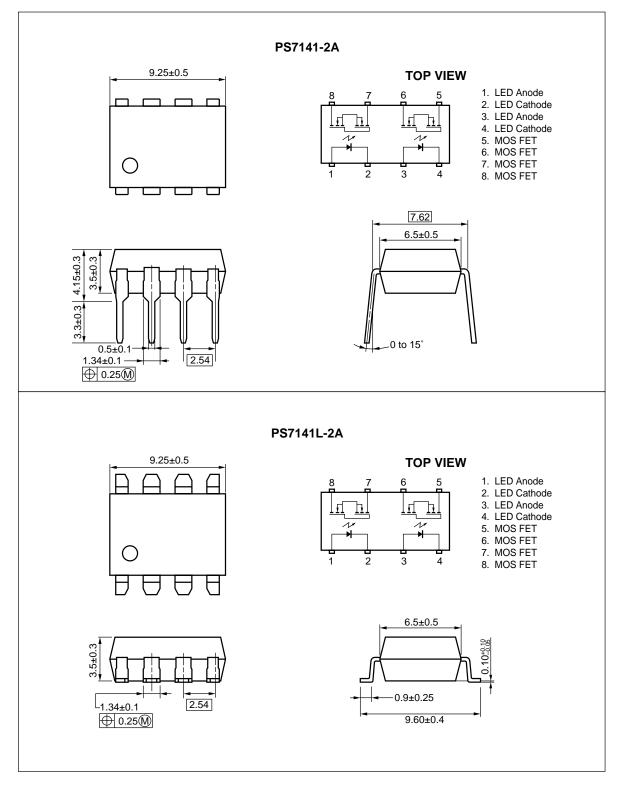
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The mark <R> shows major revised points.

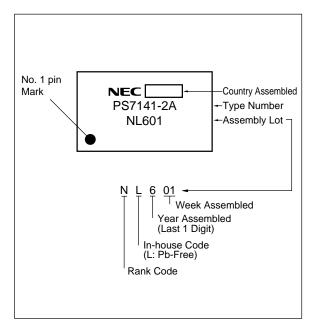
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The revised points can be easily searched by copying an "<R>" in the PDF file and specifying it in the "Find what:" field.

PACKAGE DIMENSIONS (in millimeters)



<R> MARKING EXAMPLE



<R> ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}
PS7141-2A	PS7141-2A-A	Pb-Free	Magazine case 50 pcs	Standard products	PS7141-2A
PS7141L-2A	PS7141L-2A-A			(UL, BSI, CSA	
PS7141L-2A-E3	PS7141L-2A-E3-A		Embossed Tape 1 000 pcs/reel	approved)	
PS7141L-2A-E4	PS7141L-2A-E4-A				

*1 For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (TA = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Forward Current (DC)	lf	50	mA/ch
	Reverse Voltage	VR	5.0	V
	Power Dissipation	PD	50	mW/ch
	Peak Forward Current *1	IFP	1	A/ch
MOS FET	Break Down Voltage	VL	400	V
	Continuous Load Current	١L	150	mA/ch
	Pulse Load Current ^{*2} (AC/DC Connection)	Ilp	300	mA/ch
	Power Dissipation	PD	375	mW/ch
Isolation Voltage *3		BV	1 500	Vr.m.s.
Total Power Dissipation		Ρτ	850	mW
Operating Ambient Temperature		TA	-40 to +85	°C
Storage Temperature		Tstg	-40 to +100	°C

*1 PW = 100 μ s, Duty Cycle = 1%

*2 PW = 100 ms, 1 shot

*3 AC voltage for 1 minute at $T_A = 25^{\circ}$ C, RH = 60% between input and output. Pins 1-4 shorted together, 5-8 shorted together.

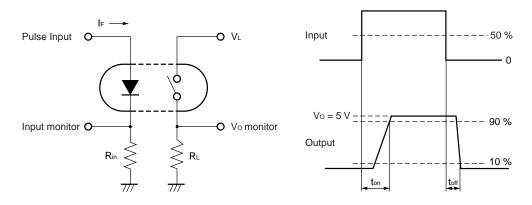
RECOMMENDED OPERATING CONDITIONS (TA = 25°C)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
LED Operating Current	lf	2	10	20	mA
LED Off Voltage	VF	0		0.5	V

	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	VF	IF = 10 mA		1.2	1.4	V
	Reverse Current	Ir	V _R = 5 V			5.0	μA
MOS FET	Off-state Leakage Current	Loff	V _D = 400 V		0.03	1.0	μA
	Output Capacitance	Cout	V _D = 0 V, f = 1 MHz		65		pF/ch
Coupled	LED On-state Current	Fon	l∟ = 150 mA			2.0	mA
	On-state Resistance	Ron1	IF = 10 mA, IL = 10 mA		20	30	Ω
		Ron2	I_{F} = 10 mA, I_{L} = 150 mA, $t \leq$ 10 ms		16	25	
	Turn-on Time *1, 2	ton	IF = 10 mA, Vo = 5 V, RL = 500 Ω,		0.35	1.0	ms
	Turn-off Time *1, 2	toff	PW ≥ 10 ms		0.06	0.2	
	Isolation Resistance	Ri-o	VI-O = 1.0 kVDC	10 ⁹			Ω
	Isolation Capacitance	CI-0	V = 0 V, f = 1 MHz		1.1		pF/ch

ELECTRICAL CHARACTERISTICS (TA = 25°C)

*1 Test Circuit for Switching Time



<R> *2 The turn-on time and turn-off time are specified as input-pulse width ≥ 10 ms. Be aware that when the device operates with an input-pulse width less than 10 ms, the turn-on time and turn-off time will increase.

75⁸⁵

f = 1 MHz

100

I⊧ = 10 mA

2.0

120

4.0

100

0

25

40

60

Applied Voltage VD (V)

200

100

-100

-200

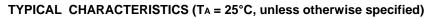
Load Voltage VL (V)

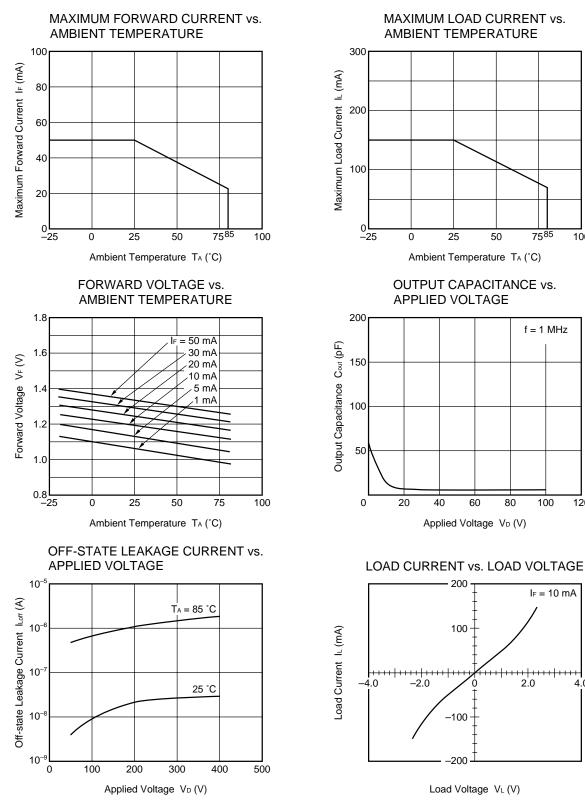
-2.0

80

Ambient Temperature TA (°C)

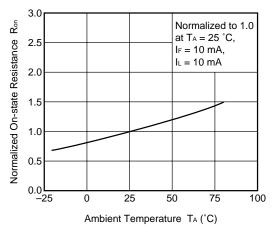
50



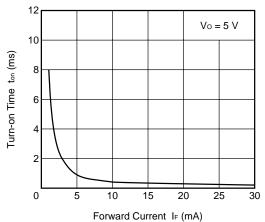


Remark The graphs indicate nominal characteristics.

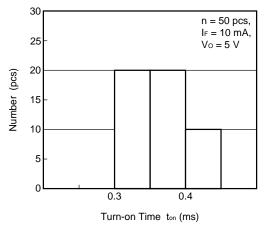
NORMALIZED ON-STATE RESISTANCE vs. AMBIENT TEMPERATURE



TURN-ON TIME vs. FORWARD CURRENT

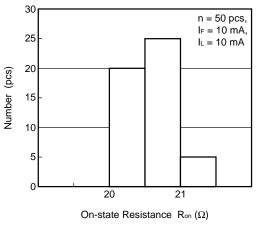


TURN-ON TIME DISTRIBUTION

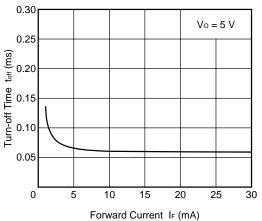


Remark The graphs indicate nominal characteristics.

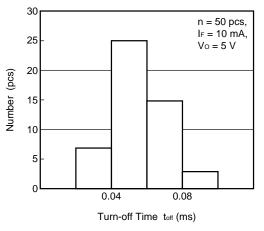


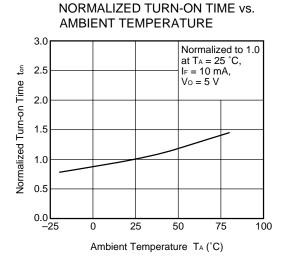


TURN-OFF TIME vs. FORWARD CURRENT

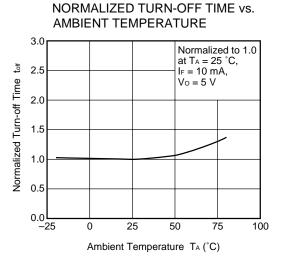


TURN-OFF TIME DISTRIBUTION

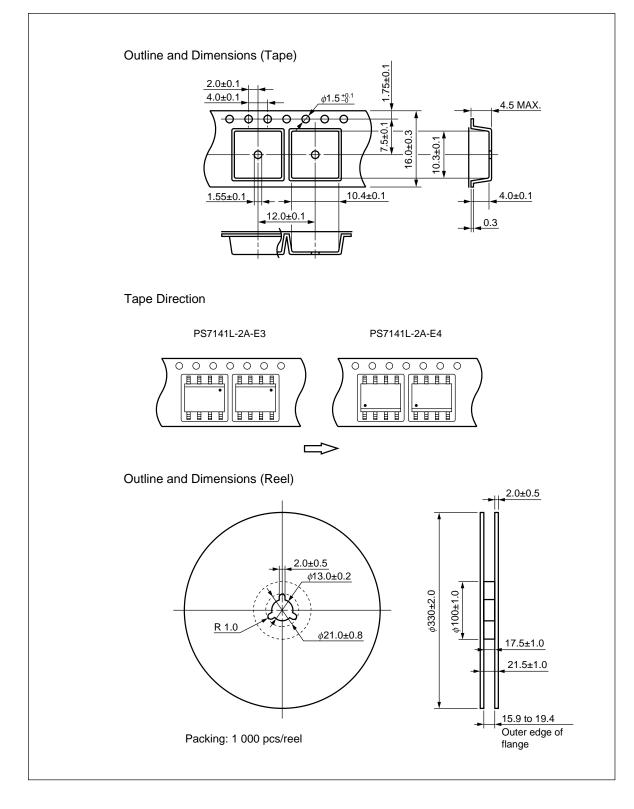




Remark The graphs indicate nominal characteristics.



TAPING SPECIFICATIONS (in millimeters)



Data Sheet PN10281EJ02V0DS

RECOMMENDED SOLDERING CONDITIONS

(1) Infrared reflow soldering

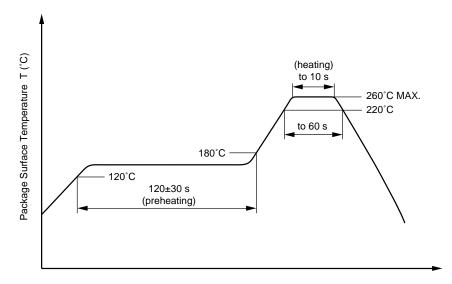
- Peak reflow temperature
- Time of peak reflow temperature
- Time of temperature higher than 220°C
- Time to preheat temperature from 120 to 180°C
- Number of reflows
- Flux

10 seconds or less 60 seconds or less 120±30 s Three Rosin flux containing small amount of chlorine (The flux with a

260°C or below (package surface temperature)

maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



Time (s)

(2) Wave soldering

260°C or below (molten solder temperature)
10 seconds or less
120°C or below (package surface temperature)
One
Rosin flux containing small amount of chlorine (The flux with a maximum chlorine

<R> (3) Soldering by soldering iron

 Peak temperature (lead part temperature) 	350°C or below
Time (each pins)	3 seconds or less
• Flux	Rosin flux containing small amount of chlorine (The flux with a
	maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

content of 0.2 Wt% is recommended.)

(b) Please be sure that the temperature of the package would not be heated over 100° C.

(4) Cautions

Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

<R> USAGE CAUTIONS

- **1.** Protect against static electricity when handling.
- 2. Avoid storage at a high temperature and high humidity.

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M8E 02.11-1

Caution GaAs Products	This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.
	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.

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